

# A3RS91.1

## High Power Chip Termination

### 100 Watts

**RoHS**  
Compliant

**AEROFLEX**  
A passion for performance.

When properly mounted on an appropriate heat sink, this chip device provides high power dissipation capabilities. Ideal for ferrite isolator applications, the improved thin film design technology and laser trimming provide proven RF power capabilities to meet the demands of today's CDMA and WCDMA system requirements. Aluminum Nitride is featured for those applications where the use and disposal of Beryllium oxide is a concern.

- Environmentally friendly AlN substrate
- High performance, thin film element
- Power 100 Watts
- New adhesion process results in improved terminal strength
- On-chip matching network improves frequency performance over the DC-3 GHz frequency range

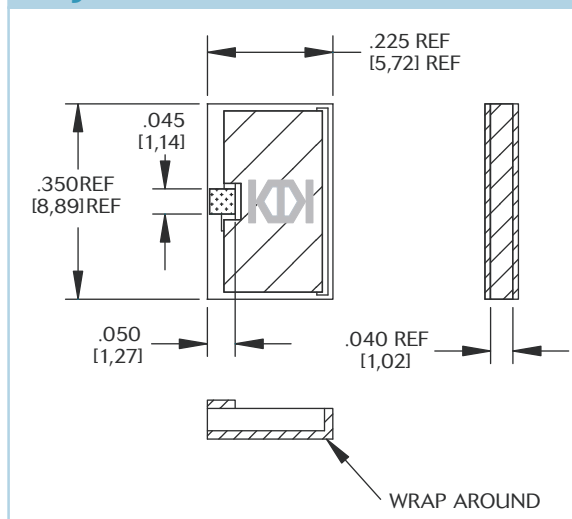


### SPECIFICATIONS

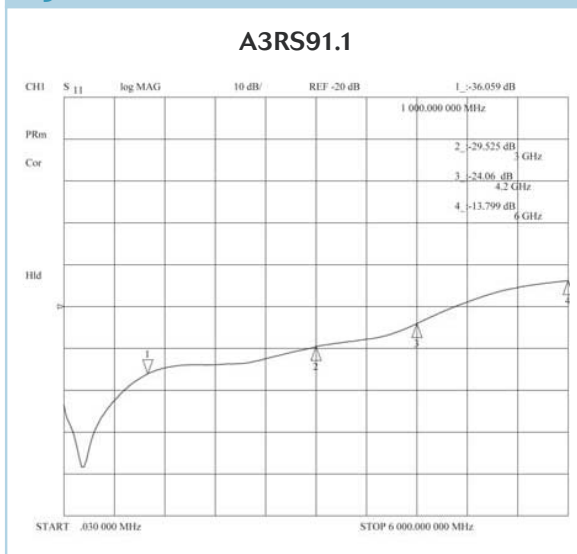
Parameters	Specifications
Frequency Range	DC to 3 GHz
Power	100 Watts*
VSWR	1.10:1 max
Resistance	50 Ohms +/- 5%
Operating Temperature	-55 °C to 150 °C
Substrate	Aluminum Nitride

\* Refer to average power derating curve chart.

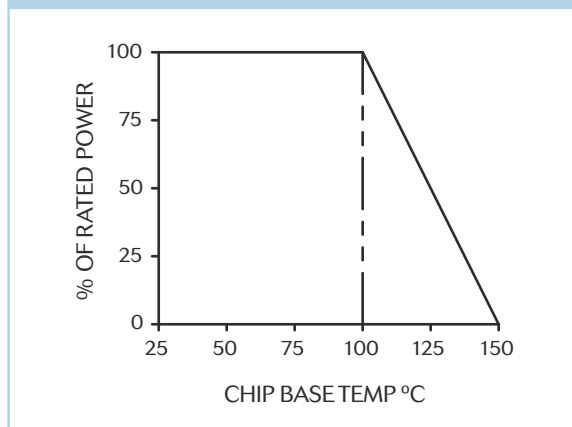
### PHYSICAL DIMENSIONS



### TYPICAL PERFORMANCE



### AVERAGE POWER DERATING CURVE



KEY: Inches [Millimeters] .XX ±.03 .XXX ±.010 [X ±0.8 .XX ±0.25]

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